

ADDITIONAL TECHNICAL INFORMATION

ADHESIVES FOR SIKABLOCK® BONDING

CHOOSING THE RIGHT ADHESIVE FOR SIKABLOCK® BOARDS

1 INTRODUCTION

This Additional Technical Information (ATI) provides an overview of adhesive compatibility for bonding SikaBlock® using SikaBiresin® adhesives. It outlines which adhesives are recommended for specific SikaBlock® types and details processing parameters such as temperature range, surface preparation and application conditions. The information is intended to support users in achieving reliable and durable bonding results under standard workshop conditions.

2 ADHESIVES OVERVIEW

ADHESIVES FOR SIKABLOCK® BONDING				
SikaBlock®	SikaBiresin® B200	SikaBiresin® B260	SikaBiresin® B181	SikaBiresin® B176
Design- and Styling Boards				
SikaBlock® M80	•			
SikaBlock® ML8 GY	•			
SikaBlock® M150	•			
SikaBlock® ML15 IY	•			
SikaBlock® M330	•			
SikaBlock® ML25 YW	•			
SikaBlock® M440	•	•		
SikaBlock® ML35 OE	•	•		
SikaBlock® M450 N	•	•		
SikaBlock® ML45 PK	•	•		
Model Boards				
SikaBlock® M600 N		•		
SikaBlock® M700 N		•		
SikaBlock® PROLAB 65 N		•		
SikaBlock® PROLAB 650 N		•		

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Tooling Boards				
SikaBlock® M930			•	
SikaBlock® M935			•	
SikaBlock® M945			•	
SikaBlock® LAB 925			•	
SikaBlock® M960			•	
SikaBlock® LAB 850			•	
SikaBlock® M980			•	
SikaBlock® M995			•	
SikaBlock® LAB 1000			•	
SikaBlock® M1700			•	
SikaBlock® M1000			•	
SikaBlock® M1050			•	
Epoxy Boards				
SikaBlock® M976 EP				•
LAB 975 New				•

3 PROCESSING

- The material and processing temperature shall be between 18 °C – 25 °C.
- Before application of adhesive ensure surfaces are clean, dry, free of dust and grease. Grinding of the surfaces can increase adhesion.
- The components of the adhesive must be mixed thoroughly before use and applied by brush or toothed spatula on both surfaces.
- Glued parts shall be clamped together with adequate force to ensure that the bonding-joint area has a thickness of approx. 0.2 mm and is free of air bubbles.
- Containers must be closed tightly immediately after use to prevent moisture ingress. The residual material needs to be used as soon as possible.
- For additional details, refer to the Product Data Sheet of the respective adhesive.

Disclaimer

The information contained herein and any other advice are given in good faith based on Sika's current knowledge and experience of the products when properly stored, handled and applied under normal conditions in accordance with Sika's recommendations. The information only applies to the application(s) and product(s) expressly referred to herein. In case of changes in the parameters of the application, such as changes in substrates etc., or in case of a different application, consult Sika's Technical Service prior to using Sika products. The information contained herein does not relieve the user of the products from testing them for the intended application and purpose. All orders are accepted subject to our current terms of sale and delivery. Users must always refer to the most recent issue of the local Product Data Sheet for the product concerned, copies of which will be supplied on request.

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